



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re the Application of: NAKAYAMA, Akitaka et al.

Group Art Unit: 1765

Serial No.: 09/713,036

Examiner: AHMED, SHAMIN

Filed: November 16, 2000

P.T.O. Confirmation No.: 3155

For. **METHOD OF MANUFACTURING MULTI-LAYER PRINTED WIRING BOARD**

AMENDMENT UNDER 37 CFR §1.111

Commissioner for Patents  
Washington, D.C. 20231

December 4, 2002

Sir:

In response to the Office Action dated **July 5, 2002**, extended to **December 5, 2002** by a 2 month Petition for Extension of Time, please amend the above-identified application as follows:

IN THE CLAIMS:

Please **CANCEL** claims 14-16 without prejudice or disclaimer.

Please **AMEND** the claims 1 and 5-13 as follows:

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TC 1700

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A1  
1. (Amended) A method of manufacturing a multi-layer printed wiring board comprising an internal layer circuit forming step, an outer layer circuit forming step, and a solder resist forming step,

wherein the internal layer circuit forming step and the outer layer circuit forming step comprise steps of:

providing a board coated with a patterning material;

coating the surface of the patterning material with a photosensitive film;